73. The device of claim 72 where the planar layer does not extend substantially up the sidewall from the bottom surface.

74. The device of claim 71 where the planar layer is an alloy or a composite.

75. The device of claim 71 where the planar layer includes a silicide.

76. The device of claim 75 where the planar layer includes a refractory metal.

77. In a semiconductor device having a substrate, a contact hole in a layer of insulator material directly overlying the substrate, the hole comprising:

a bottom surface having at least one bottom layer of conductive material including at least two different constituent elements and having a thickness variation less than about 50%; and

a vertical sidewall consisting substantially entirely of the aforementioned layer of insulator material.

78. The device of claim 77 where the hole has a high aspect ratio.

79. The device of claim 78 where the aspect ratio is at least 4.

80. The device of claim 77 where the thickness variation is less than about 20%.

81. The device of claim 80 where the thickness variation is less than about 10%.

82. In a semiconductor device having a substrate, a contact hole in a layer of insulator material directly overlying the substrate, the hole comprising:

a vertical sidewall consisting substantially entirely of the aforementioned layer of insulator material; and

a bottom surface having at least one generally planar bottom layer of conductive material having a graded stoichiometry between two different constituent elements in the bottom layer.

83. The device of claim 82 where the substrate is silicon and the insulator material is an oxide, a nitride, or a glass.

84. The device of claim 82 where the planar layer comprises multiple layers having mutually different stoichiometries.

85. The device of claim 82 where the conductive material includes a silicide of a metal.

86. The device of claim 85 where the metal is a refractory metal.

87. In a semiconductor device having a substrate, a contact hole in a layer of insulator material directly overlying the substrate, the hole comprising:

a bottom surface having at least one generally planar bottom layer of a conductive material including at least two different constituent elements; and

a vertical sidewall comprising the aforementioned layer of insulator material and being free of the conductive elements.

88. The device of claim 87 where the planar layer contacts the lower end of the sidewall.

89. The device of claim 88 where the planar layer does not extend substantially up the sidewall from the bottom surface.

90. The device of claim 87 where the planar layer is an alloy or a composite.

91. The device of claim 87 where the planar layer includes a silicide.

92. The device of claim 91 where the planar layer includes a refractory metal.

93. In a semiconductor device having a substrate, a contact hole in a layer of insulator material directly overlying the substrate, the hole comprising:
and

a bottom surface having at least one generally planar bottom layer of conductive material including a silicide of a metal,

a vertical sidewall comprising the aforementioned layer of insulator material, and being substantially free of the metal.

94. The device of claim 93 where the metal is a refractory metal.

95. The device of claim 93 where the insulator material is an oxide, a nitride, or a glass.

96. The device of claim 93 where the planar layer has a graded stoichiometry.

97. The device of claim 96 where the planar layer comprises multiple layers having mutually different stoichiometries.

98. An integrated circuit, comprising:

a substrate;

a layer of insulating material overlying the substrate and containing at least one contact hole having only that layer as a sidewall and having a bottom surface contacting the substrate; and

at least one generally planar layer of conductive material including at least two different constituent elements covering the bottom surface of the hole.

99. The integrated circuit of claim 98 where the planar layer contacts the lower end of the sidewall.

100. The integrated circuit of claim 99 where the planar layer does not extend substantially up the sidewall from the bottom surface.

101. The integrated circuit of claim 98 where the planar layer is an alloy or a composite.

102. The integrated circuit of claim 98 where the planar layer includes a silicide.

103. The integrated circuit of claim 102 where the planar layer includes a refractory metal.

104. An integrated circuit, comprising:

a substrate;

a layer of insulating material overlying the substrate and containing at least one contact hole having only that layer as a sidewall and having a bottom surface contacting the substrate; and

at least one generally planar layer of conductive material covering the bottom surface, the planar layer including a silicide of a metal, the metal being substantially entirely confined to the bottom surface in the hole.